

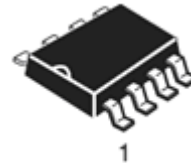
N-Channel MOSFET MEM2306

General Description

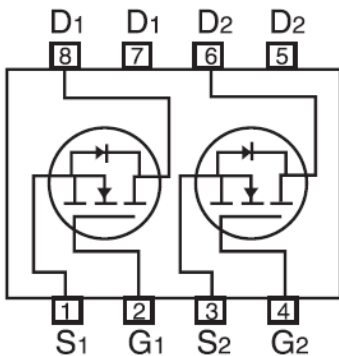
MEM2306SG Series Dual N-channel enhancement mode field-effect transistor produced with high cell density DMOS trench technology, which is especially used to minimize on-state resistance. This device particularly suits low voltage applications, and low power dissipation.

Features

- 20V/5A,
 $R_{DS(ON)}=29m\Omega @ V_{GS}=3.85V, I_D=5A$
- High Density Cell Design For Ultra Low On-Resistance
- surface mount package: SOP8



Pin Configuration



Typical Application

- Battery management
- power management
- Portable equipment
- Low power DC to DC converter.
- Load switch
- LCD adapter

Absolute Maximum Ratings

Parameter		Symbol	Ratings	Unit
Drain-Source Voltage		V_{DSS}	20	V
Gate-Source Voltage		V_{GSS}	± 12	V
Drain Current	$T_A=25^\circ C$	I_D	5	A
Pulsed Drain Current ^{1,2}		I_{DM}	30	A
Total Power Dissipation	$T_A=25^\circ C$	P_D	1.3	W
	$T_A=70^\circ C$		1.0	
Operating Temperature Range		T_{Opr}	150	$^\circ C$
Storage Temperature Range		T_{stg}	-65/150	$^\circ C$

Thermal Characteristics

Parameter		Symbol	Ratings	Unit
Thermal Resistance, Junction-to-Ambient ³	Steady-State	$R_{\theta JA}$	62.5	$^{\circ}C/W$

Electrical Characteristics

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	20	23		V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.72	1	V
Gate-Body Leakage	I_{GSS}	$V_{DS}=0V, V_{GS}=12V$		5	100	nA
		$V_{DS}=0V, V_{GS}=-12V$		-7	-100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=16V, V_{GS}=0V$		1.8	1000	nA
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=6A$			23	m Ω
		$V_{GS}=3.85V, I_D=5A$			25	m Ω
		$V_{GS}=2.5V, I_D=4A$			35	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=10V, I_D=6A$	6	20		S
Source-drain (diode forward) voltage	V_{SD}	$V_{GS}=0V, I_S=1.5A$		0.8	1	V
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=8V, V_{GS}=0V, f=1MHz$		1120	1500	pF
Output Capacitance	C_{oss}			480	630	
Reverse Transfer Capacitance	C_{rss}			110	160	
Switching Characteristics						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=10V, RL=10\Omega, I_D=1A, V_{GEN}=4.5V, R_g=6\Omega$		25	60	ns
Rise Time	t_r			60	140	
Turn-Off Delay Time	$t_{d(off)}$			60	140	
Fall-Time	t_f			50	60	
Total Gate Charge	Q_g	$V_{DS}=10V, V_{GS}=4.5V, I_D=6A$		47	60	nC
Gate-Source Charge	Q_{gs}			6		
Gate-Drain Charge	Q_{gd}			8		

Typical Performance Characteristics:

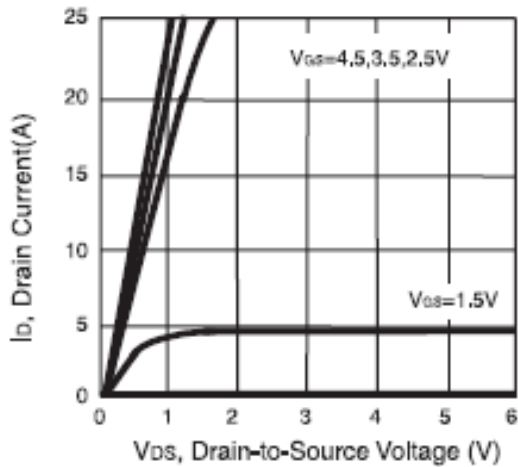


Figure 1. Output Characteristics

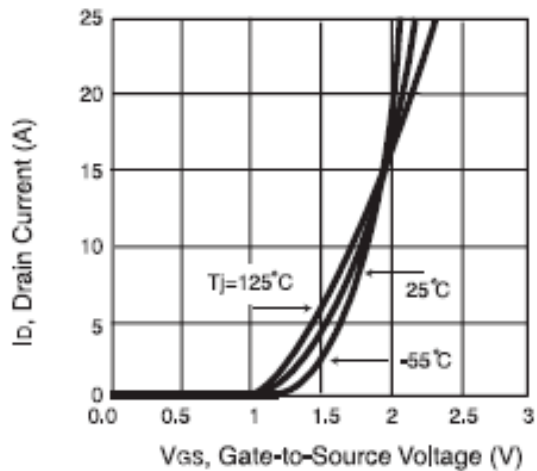


Figure 2. Transfer Characteristics

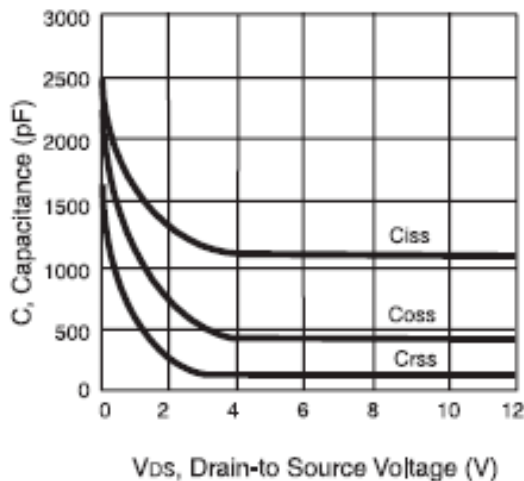


Figure 3. Capacitance

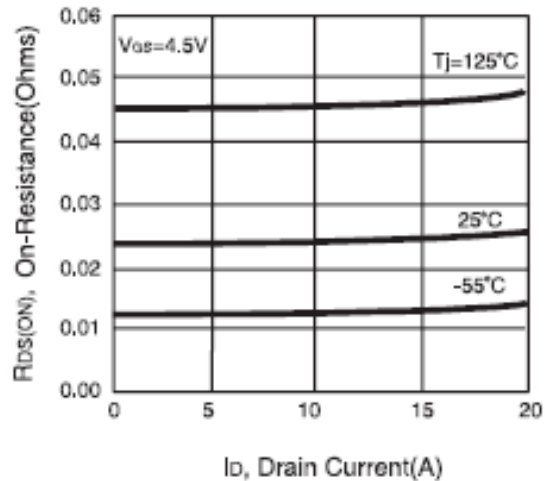


Figure 4. On-Resistance Variation with Drain Current and Temperature

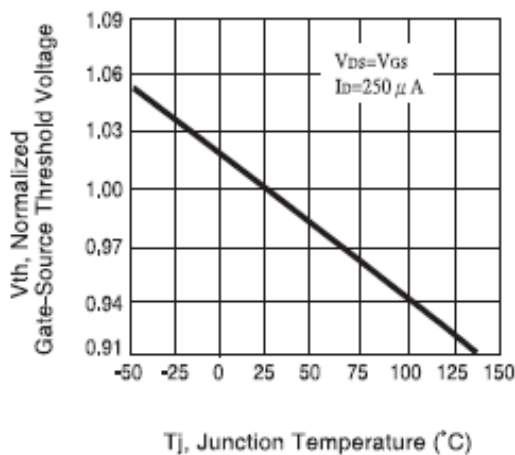


Figure 5. Gate Threshold Variation with Temperature

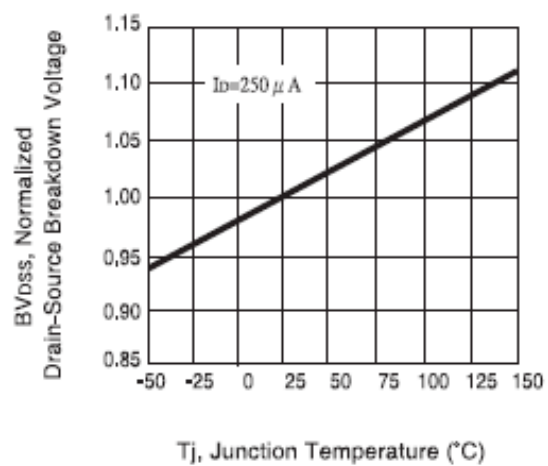


Figure 6. Breakdown Voltage Variation with Temperature

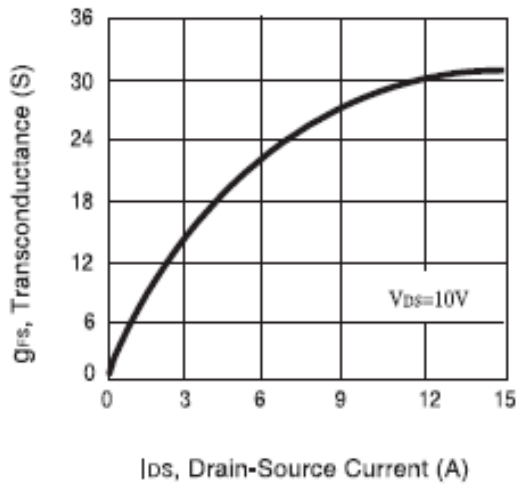


Figure 7. Transconductance Variation with Drain Current

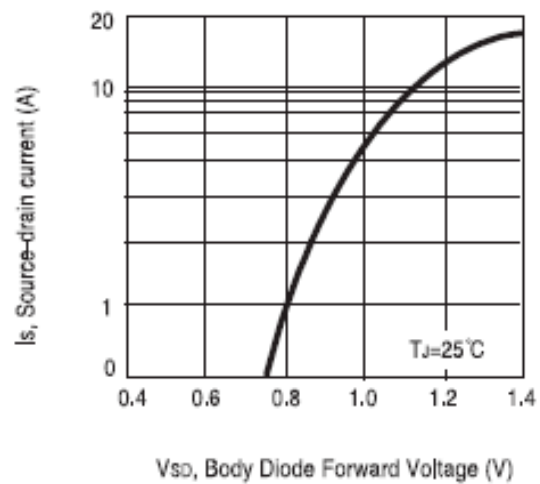


Figure 8. Body Diode Forward Voltage Variation with Source Current

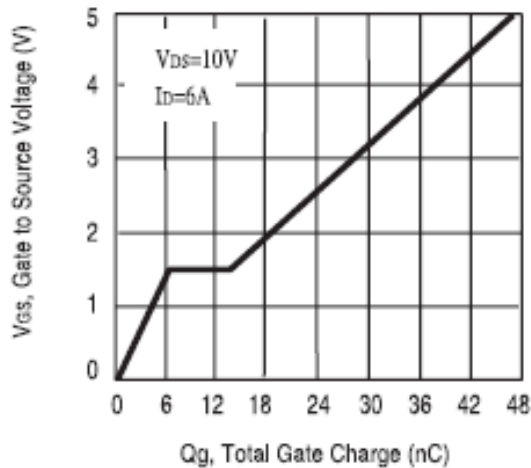


Figure 9. Gate Charge

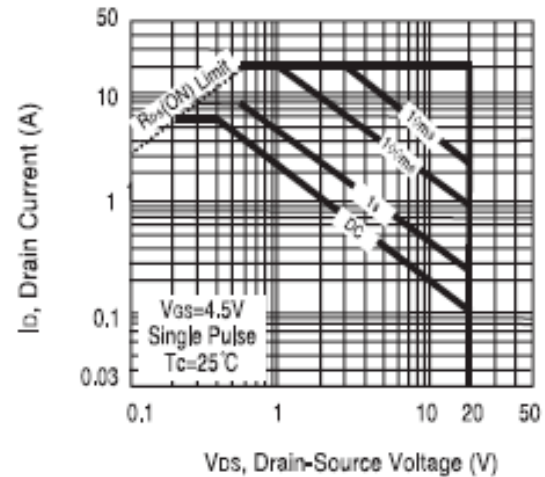


Figure 10. Maximum Safe Operating Area

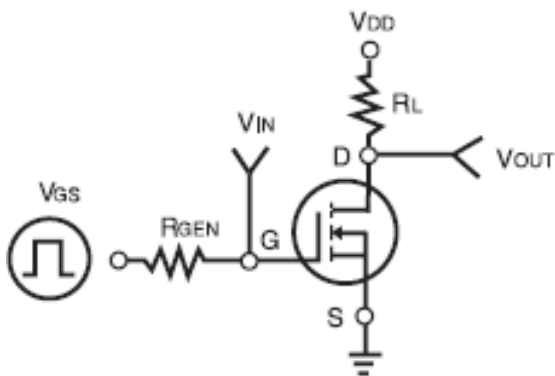


Figure 11. Switching Test Circuit

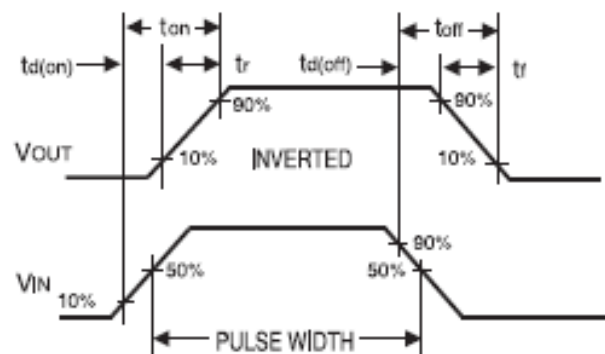


Figure 12. Switching Waveforms

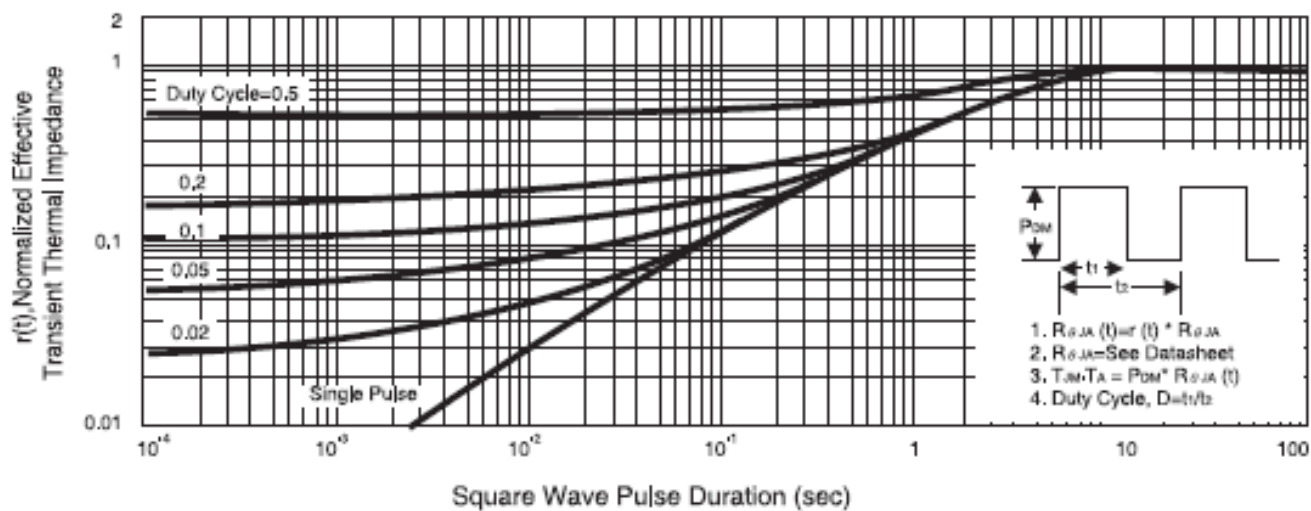
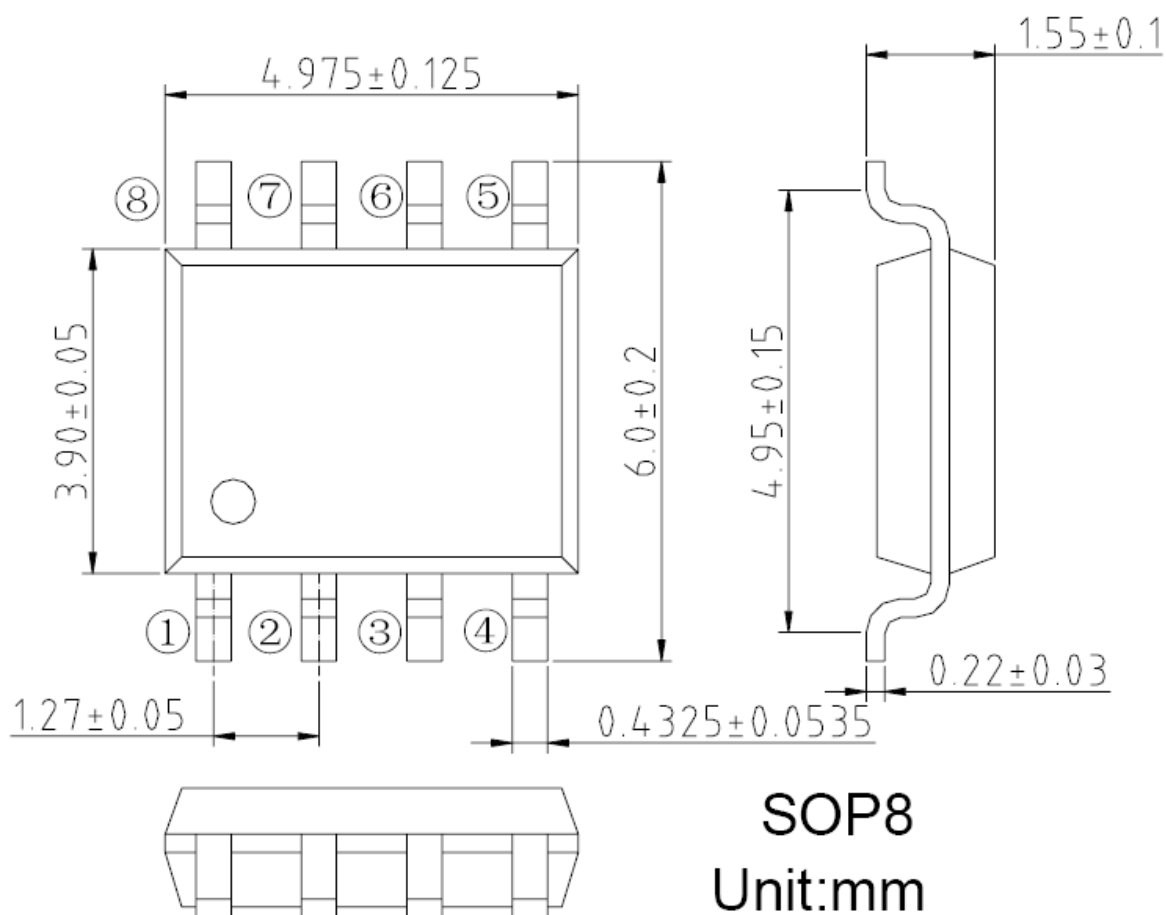


Figure 13. Normalized Thermal Transient Impedance Curve

Package Information:



- The information described herein is subject to change without notice.
- Nanjing Micro One Electronics Inc is not responsible for any problems caused by circuits or diagrams described herein whose related industrial properties, patents, or other rights belong to third parties. The application circuit examples explain typical applications of the products, and do not guarantee the success of any specific mass-production design.
- Use of the information described herein for other purposes and/or reproduction or copying without the express permission of Nanjing Micro One Electronics Inc is strictly prohibited.
- The products described herein cannot be used as part of any device or equipment affecting the human body, such as exercise equipment, medical equipment, security systems, gas equipment, or any apparatus installed in airplanes and other vehicles, without prior written permission of Nanjing Micro One Electronics Inc.
- Although Nanjing Micro One Electronics Inc exerts the greatest possible effort to ensure high quality and reliability, the failure or malfunction of semiconductor products may occur. The user of these products should therefore give thorough consideration to safety design, including redundancy, fire-prevention measures, and malfunction prevention, to prevent any accidents, fires, or community damage that may ensue.